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With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

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Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

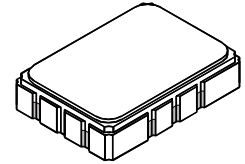
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



SF2151B

211.2 MHz SAW Filter



SMP-03-S

- IF SAW Filter, 211.2 MHz, 20 MHz BW
- Low-loss Filter for WCDMA applications
- 5.0 X 7.0 x 1.7 mm Surface-mount Case
- Complies with Directive 2002/95/EC (RoHS)



Absolute Maximum Ratings

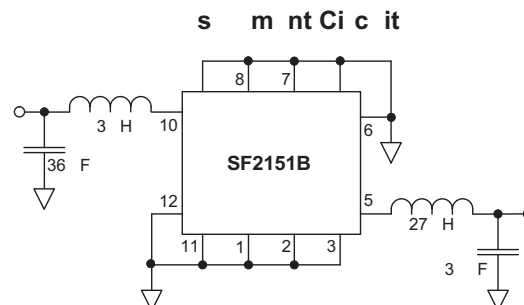
Rating	Value	Units
Maximum Incident Power in Passband	+10	dBm
Maximum DC Voltage Between any Two Terminals	30	VDC
Storage Temperature Range in Tape and Reel	-40 to +85	°C
Maximum Soldering Temperature	265 °C for 10 s	

Electrical Characteristics

Characteristic	Sym	Notes	Min	Typ	Max	Units
Nominal Center Frequency	f_C	1	211.2			MHz
Insertion Attenuation	α_{min}			13.5	16.0	dB
Amplitude Ripple (p-p)	$f_C \pm 9.42$ MHz	$\Delta\alpha$	1	0.35	1.5	
	$f_C \pm 10.00$ MHz			0.45	2.0	
Group Delay Ripple (p-p)	$f_C \pm 10.00$ MHz	$\Delta\tau$	1	20	100	ns
Group Delay	at f_C	τ		700	800	
VSWR	$f_C \pm 10.00$ MHz			1.2:1	2:1	
Relative Attenuation (relative to α_{min})	10 to 100 MHz		50			dB
	100 to 168 MHz		53			dB
	168 to 196.5 MHz		20			dB
	260 to 270 MHz		48			dB
	270 to 360 MHz		45			dB
Operating Temperature Range	T_A	1	-40		+85	°C
Case Style		5	SMP-03-S 7 x 5 mm Nominal Footprint			
Lid Symbolization (YY=year, WW=week, S=shift) See note 4			RFM SF2151 YYWWS			

Electrical Connections

Connection	Terminals
Input	10
Output	5
Ground	All Others

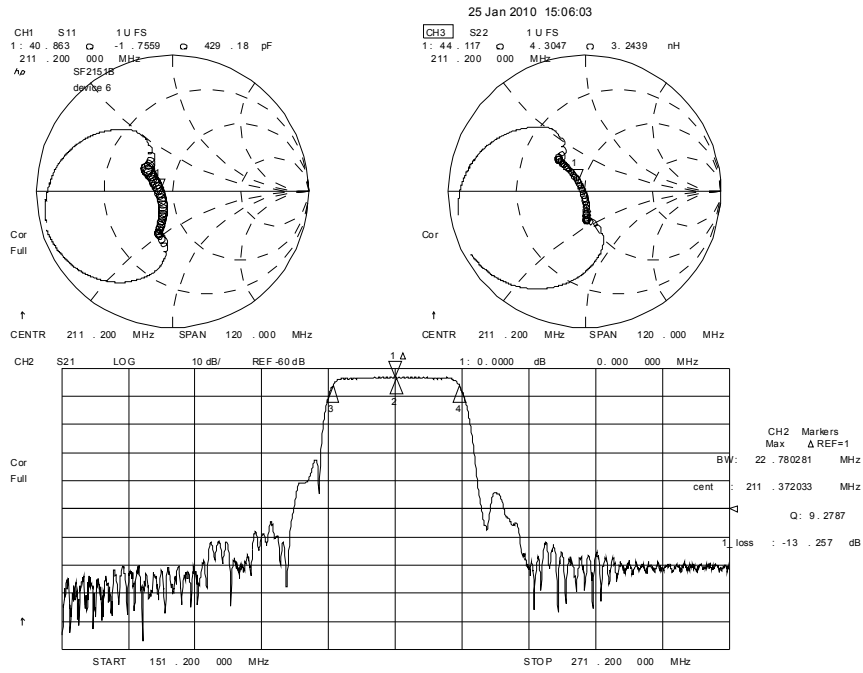


CAUTION: Electrostatic Sensitive Device. Observe precautions for handling.

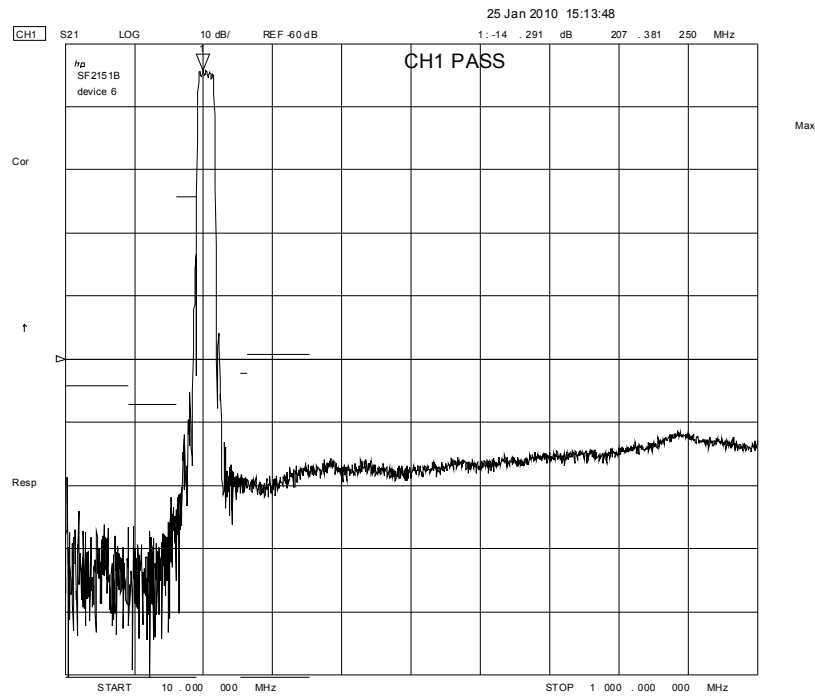
NOTES:

1. Unless noted otherwise, all specifications apply over the operating temperature range with filter soldered to the specified demonstration board with impedance matching to 50 Ω and measured with 50 Ω network analyzer.
2. Unless noted otherwise, all frequency specifications are referenced to the nominal center frequency, f_C .
3. Rejection is measured as attenuation below the minimum IL point in the passband. Rejection in final user application is dependent on PCB layout and external impedance matching design. See Application Note No. 42 for details.
4. The design, manufacturing process, and specifications of this filter are subject to change.
5. Tape and Reel Standard Per ANSI / EIA 481.
6. Either Port 1 or Port 2 may be used for either input or output in the design. However, impedances and impedance matching may vary between Port 1 and Port 2, so that the filter must always be installed in one direction per the circuit design.
7. US and international patents may apply.
8. Murata, stylized Murata logo, and Murata N.A., Inc. are registered trademarks of Murata Manufacturing Co., Ltd.

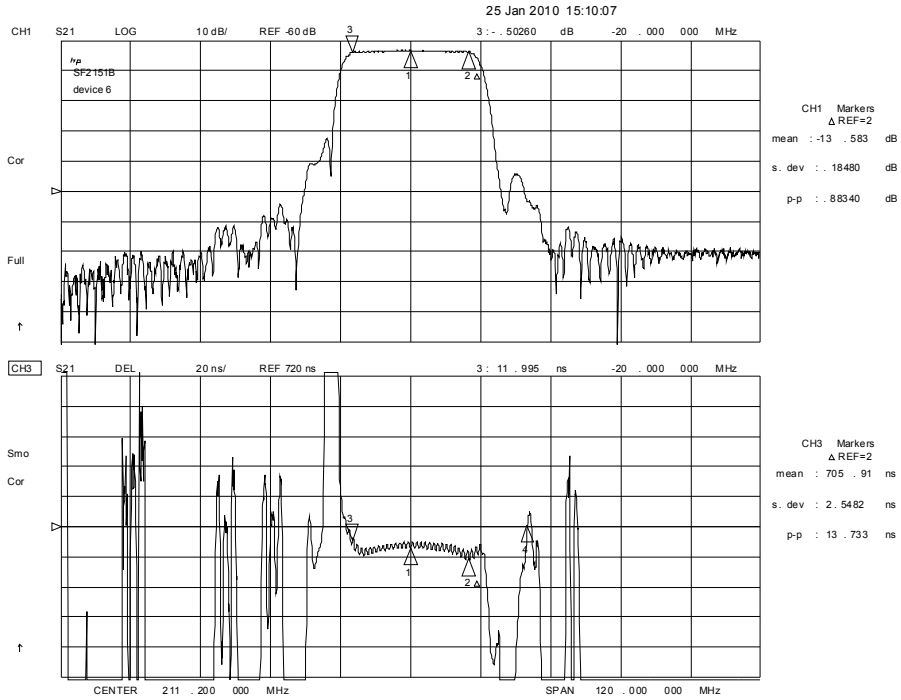
Filter Response and Impedance Plots



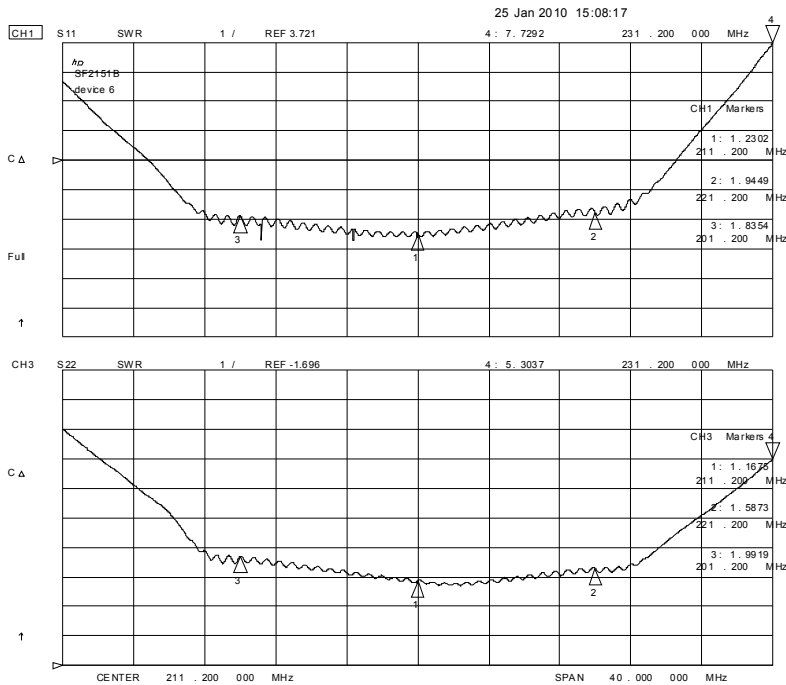
Filter Ultimate Rejection Plot



Filter Passband Group Delay and Amplitude Plots



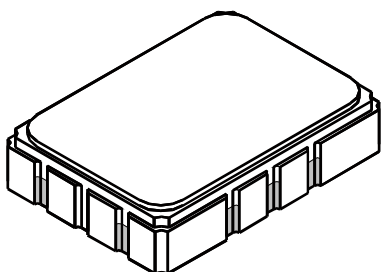
Filter Input and Output VSWR Plots (matched)



SMP-03-S Case

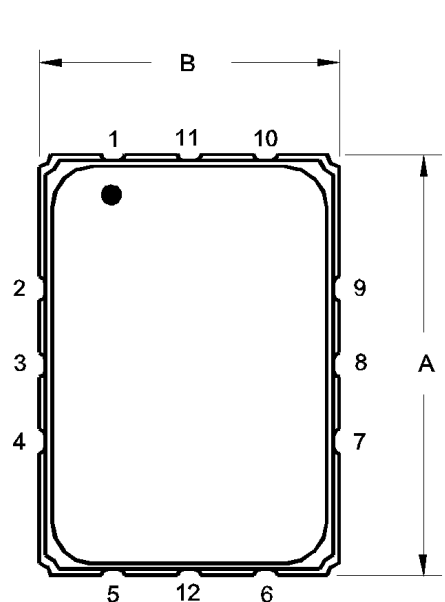
12-Terminal Ceramic Surface-Mount Case

5 x 7 mm Nominal Footprint

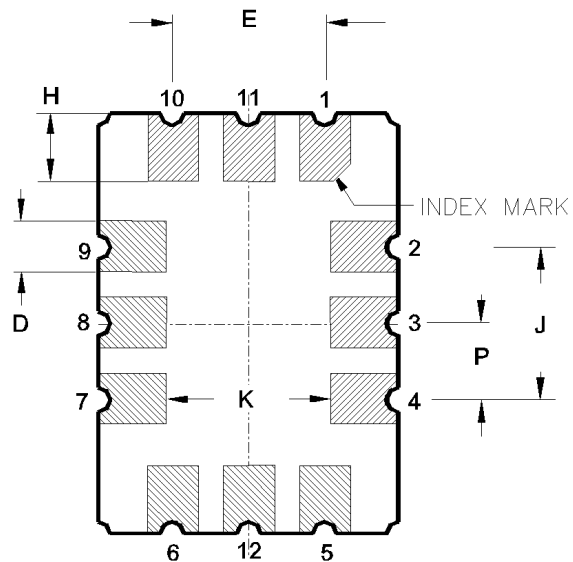
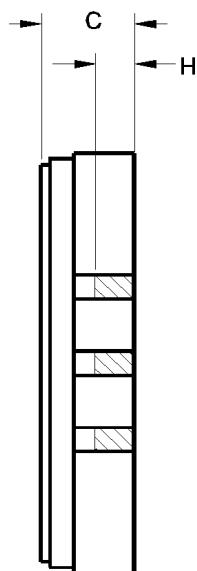


Case Dimensions						
Dimension	mm			Inches		
	Min	Nom	Max	Min	Nom	Max
A	6.80	7.00	7.20	0.268	0.276	0.283
B	4.80	5.00	5.20	0.189	0.197	0.205
C		1.65	2.00		0.065	0.079
D		0.80				
E	2.41	2.54	2.67	0.095	0.100	0.105
H	0.87	1.1	1.13	0.034	0.039	0.044
J		2.54				
K	2.87	3.00	3.13	0.113	0.118	0.123
P	1.14	1.27	1.40	0.045	0.050	0.055

Materials	
Solder Pad Plating	0.3 to 1.0 μm Gold over 1.27 to 8.89 μm Nickel
Lid Plating	2.0 to 3.0 μm Nickel
Body	Al_2O_3 Ceramic
Pb Free	

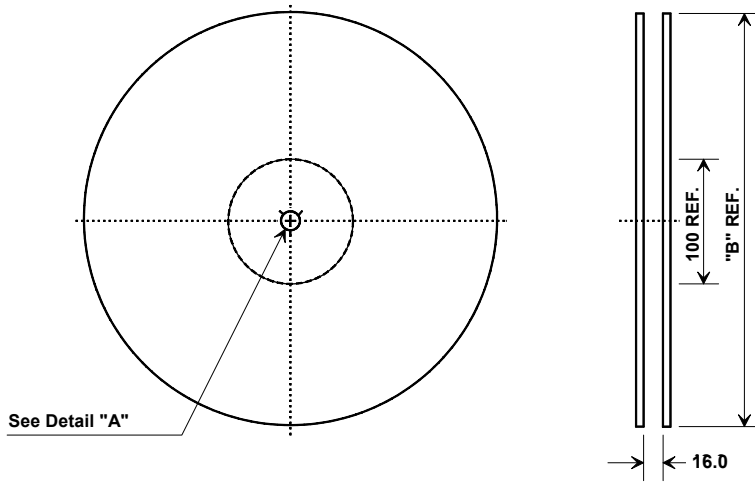


TOP VIEW

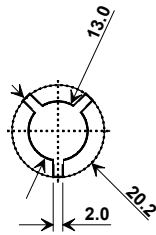


BOTTOM VIEW

Tape and Reel Specifications



"B"		Quantity Per Reel
Inches	millimeters	
7	178	500
13	330	2000



COMPONENT ORIENTATION and DIMENSIONS

Carrier Tape Dimensions	
Ao	5.5 mm
Bo	7.5 mm
Ko	2.0 mm
Pitch	8.0 mm
W	16.0 mm

